

ABSTRACT

A copper alloy material for parts of electronic and electric machinery and tools contains 1.0 to 3.0 mass% of Ni, 0.2 to 0.7 mass% of Si, 0.01 to 0.2 mass% of Mg, 0.05 to 1.5 mass% of Sn, 0.2 to 1.5 mass% of Zn, and less than 0.005 mass% (including 0 mass%) of S, with the balance being Cu and inevitable impurities, wherein the copper alloy material has:

- 10 (1) a specific crystal grain diameter, and a specific ratio between the longer diameters of a crystal grain on a cross section parallel or perpendicular to a direction of final plastic working; and/or
- (2) a specific surface roughness after the final plastic
- 15 working.

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